

CI
Sub D1

a mask set on the semiconductor device and having an opening at which part of the semiconductor device is exposed;

an extruding section which extrudes a fluidizing resin into the opening of the mask;

a first drive section which drives the extruding section;

a squeegee which causes a movement of the fluidizing resin present over the opening which is extruded from the extruding section into the opening; and

a second drive section which drives the squeegee.

Q2

8. (Twice Amended) A resin encapsulating apparatus for forming a protection resin sealing body on a semiconductor device in which the resin sealing body and external connection balls are formed on the same surface side of the semiconductor device, the resin encapsulating apparatus comprising:

a retaining section which retains the semiconductor device;

a mask set on the semiconductor device and having an opening at which, when the mask is set on the semiconductor device, an area of the semiconductor device at which the resin sealing body is to be formed is exposed;

an extruding section which extrudes a fluidizing resin into the opening of the mask;

a first drive section which drives the extruding section;

a squeegee which causes a movement of the fluidizing resin present over the opening which is extruded from the extruding section into the opening; and

a second drive section which drives the squeegee.

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